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ABSTRACT OF THE DISCLOSURE

An integrated circuit having at least one micromechanical element thereon is described comprising a support substrate, a sensor element electrically connected to a logic circuit, and the logic circuit electrically connected to a semiconductor visual display element.

The integrated circuit may be manufactured by a process which comprises:

- a) providing a support substrate,
- b) forming at least two elements selected from the group consisting of a micromechanical sensor element, a logic circuit and a semiconductor visual display element on said support, and
- c) manufacturing a third element on said support substrate, said third element selected from the group consisting of a micromechanical sensor element, a logic circuit and a semiconductor visual display element which was not provided in step b).

In one embodiment of the process of manufacture, all three of the at least three elements are constructed on the support itself, preferably by microlithographic processes.

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